Silicon N-Channel MOS FET

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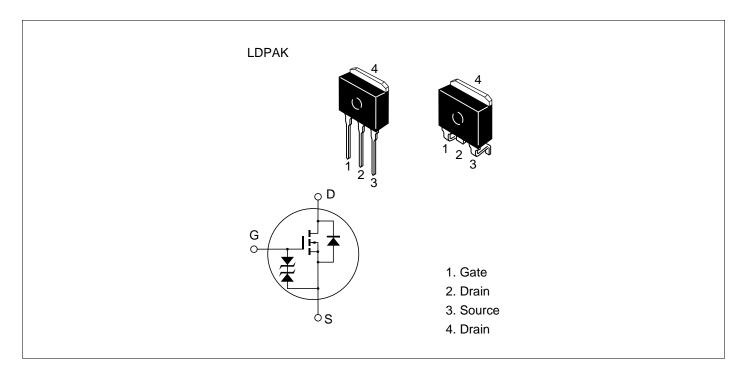
Application

High speed power switching

Features

- Low on-resistance
- High speed switching
- 4 V gate drive device
 - Can be driven from 5 V source
- Suitable for motor drive, DC-DC converter, power switch and solenoid drive

Outline





Absolute Maximum Ratings ($Ta = 25^{\circ}C$)

Item	Symbol	Ratings	Unit
Drain to source voltage	$V_{(BR)DSS}$	100	V
Gate to source voltage	V _{GSS}	±20	V
Drain current	I _D	20	A
Drain peak current	I D(pulse) * 1	80	A
Body to drain diode reverse drain current	l _{DR}	20	A
Channel dissipation	Pch*2	50	W
Channel temperature	Tch	150	°C
Storage temperature	Tstg	-55 to +150	°C

Notes 1. PW \leq 10 μ s, duty cycle \leq 1%

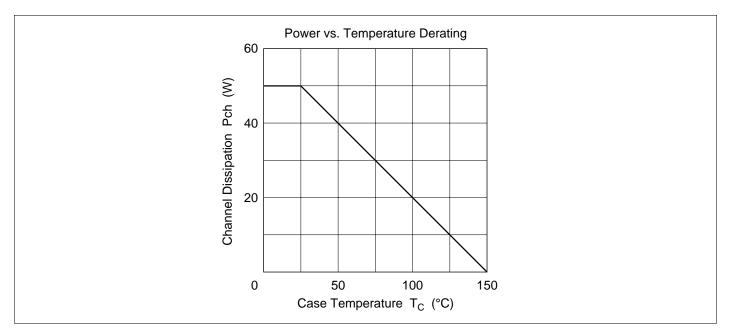
2. Value at $T_c = 25^{\circ}C$

Electrical Characteristics (Ta = 25°C)

Item	Symbol	Min	Тур	Max	Unit	Test conditions	
Drain to source breakdown voltage	$V_{(\text{BR})\text{DSS}}$	100	_	_	V	$I_{\rm D} = 10$ mA, $V_{\rm GS} = 0$	
Gate to source breakdown voltage	$V_{(BR)GSS}$	±20	—	_	V	$I_{g} = \pm 100 \ \mu A, \ V_{DS} = 0$	
Gate to source leak current	I _{GSS}			±10	μΑ	$V_{GS} = \pm 16 \text{ V}, V_{DS} = 0$	
Zero gate voltage drain current	I _{DSS}	_		250	μΑ	$V_{\rm DS} = 80 \ V, \ V_{\rm GS} = 0$	
Gate to source cutoff voltage	$V_{GS(off)}$	1.0		2.0	V	$I_{\rm D} = 1 \text{ mA}, V_{\rm DS} = 10 \text{ V}$	
Static Drain to source on state	$R_{DS(on)}$	_	0.065	0.085	Ω	$I_{\rm D} = 10 \text{ A}, \text{ V}_{\rm GS} = 10 \text{ V}^{*1}$	
resistance		_	0.085	0.12	Ω	$I_{D} = 10 \text{ A}, V_{GS} = 4 \text{ V}^{*1}$	
Forward transfer admittance	yfs	10	16	_	S	$I_{\rm D} = 10 \text{ A}, V_{\rm DS} = 10 \text{ V}^{*1}$	
Input capacitance	Ciss		1300		pF	$V_{\rm DS} = 10 \ V, \ V_{\rm GS} = 0,$	
Output capacitance	Coss	_	540	_	pF	f = 1 MHz	
Reverse transfer capacitance	Crss		160		pF		
Turn-on delay time	t _{d(on)}		12		ns	$I_{\rm D} = 10 \text{ A}, V_{\rm GS} = 10 \text{ V},$	
Rise time	t,		100		ns	$R_{L} = 3 \Omega$	
Turn-off delay time	t _{d(off)}	_	300	_	ns		
Fall time	t _f		150		ns		
Body to drain diode forward voltage	V_{DF}	—	1.3	—	V	$I_{F} = 20 \text{ A}, V_{GS} = 0$	
Body to drain diode reverse recovery time	t _{rr}	—	300	—	ns	$I_F = 20 \text{ A}, V_{GS} = 0,$ $di_F/dt = 50 \text{ A}/\mu \text{s}$	

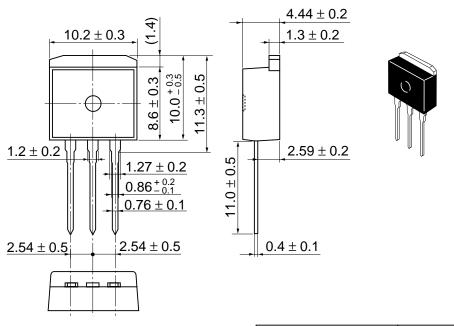
Note 1. Pulse test

See characteristic curves of 2SK1302.



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Unit: mm



Hitachi Code	LDPAK (L)
JEDEC	
EIAJ	
Weight (reference value)	1.4 g

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